

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization  
International Bureau(43) International Publication Date  
18 December 2003 (18.12.2003)

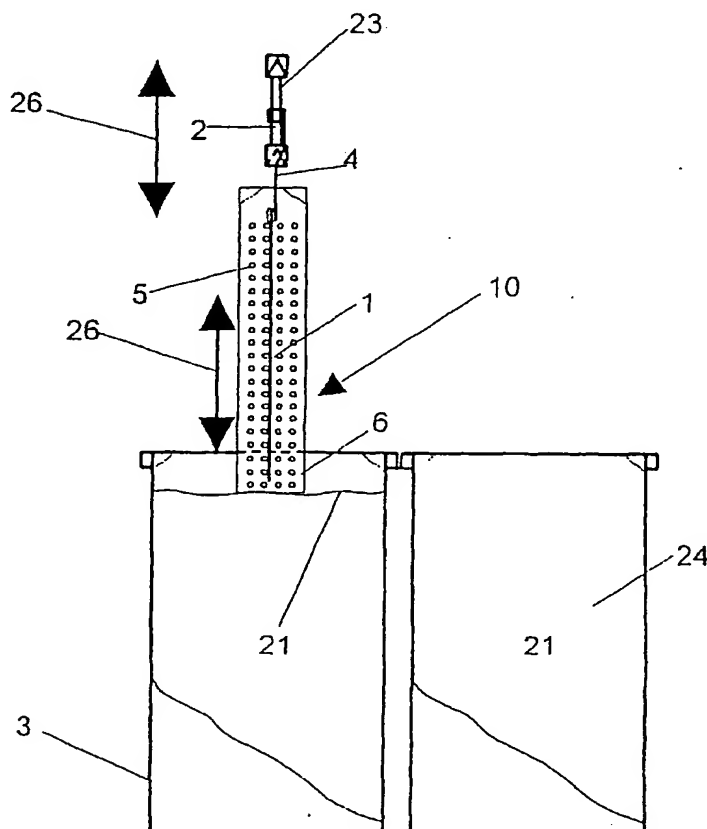
PCT

(10) International Publication Number  
WO 03/105546 A1

- (51) International Patent Classification<sup>7</sup>: H05K 3/00, C25D 17/06
- (21) International Application Number: PCT/EP03/05587
- (22) International Filing Date: 27 May 2003 (27.05.2003)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:  
102 24 817.6 5 June 2002 (05.06.2002) DE
- (71) Applicant (for all designated States except US):  
ATOTECH DEUTSCHLAND GMBH [DE/DE];  
Erasmusstrasse 20, 10553 Berlin (DE).
- (72) Inventors; and
- (75) Inventors/Applicants (for US only): SCHELLER, Britta  
[DE/DE]; Mühlfeld 63, 90559 Burghann (DE). WEX, Orlando  
[DE/DE]; Hauptstrasse 27, 90522 Oberasbach (DE).
- (74) Agent: EFFERT, BRESSEL UND KOLLEGEN;  
Radickestrasse 48, 12489 Berlin (DE).
- (81) Designated States (national): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.
- (84) Designated States (regional): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

[Continued on next page]

(54) Title: METHOD AND DEVICE FOR TREATING FLAT AND FLEXIBLE WORK PIECES



(57) **Abstract:** The device in accordance with the invention and the method serve to treat flat and flexible work pieces (1) with a fluid, preferably in electroplating plants and etching facilities. The device and the method permit to place foil-type work pieces (1) in particular in such a manner into the fluid, a wet-chemical or electrochemical processing fluid for example, that the work pieces (1) will not deform or hit the side walls of a processing tank (3) or other built-in components. For this purpose, the processing tank (3) is assigned a protective carrier (5) into which the work pieces (1) are lowered, said carrier (5) being in a largely empty condition. For treatment, the protective carrier (5) is for example lowered into a tank (3) which is filled with processing fluid, said processing fluid flowing into the protective carrier (5). Means are provided on the protective carrier (5) by means of which the processing fluid is allowed to controlledly flow into the protective carrier (5).